TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

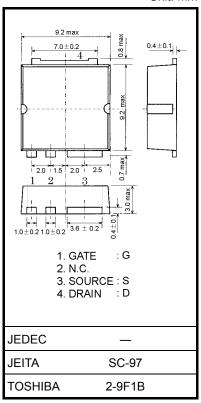
# 2SK3499

Switching Regulator and DC-DC Converter Applications Motor Drive Applications

- Low drain-source ON resistance:  $RDS(ON) = 0.4 \Omega$  (typ.)
- High forward transfer admittance:  $|\,Y_{\rm fs}\,|$  = 8.0 S (typ.)
- Low leakage current:  $I_{DSS}$  = 100  $\mu A$  (max) (V\_{DS} = 400 V)
- Enhancement model:  $V_{th}$  = 2.0 to 4.0 V (V<sub>DS</sub> = 10 V, I<sub>D</sub> = 1 mA)

# Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V <sub>DSS</sub>	400	V	
Drain-gate voltage ( $R_{GS}$ = 20 k $\Omega$ )		V <sub>DGR</sub>	400	V	
Gate-source voltage		V <sub>GSS</sub>	±30	V	
Drain current	DC (Note 1)	۱ <sub>D</sub>	10	А	
	Pulse (Note 1)	I <sub>DP</sub>	40	A	
Drain power dissipation	n (Tc = 25°C)	PD	80	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	360	mJ	
Avalanche current		I <sub>AR</sub>	10	А	
Repetitive avalanche energy (Note 3)		E <sub>AR</sub>	8	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55 to150	°C	



Weight: 0.74 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

## **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	1.56	°C/W

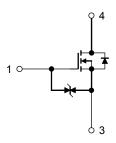
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD} = 90 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 5.85 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 10 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

## **Circuit Configuration**



Unit: mm

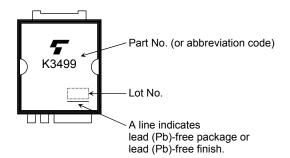
**Electrical Characteristics (Ta = 25°C)** 

Char	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS}=\pm 25~V,~V_{DS}=0~V$			±10	μA
Drain-source breakdown voltage		V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30	_		V
Drain cut-OFF current		I <sub>DSS</sub>	$V_{DS} = 400 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			100	μA
Drain-source bre	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	400			V
Gate threshold v	oltage	V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0		4.0	V
Drain-source ON	resistance	R <sub>DS (ON)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5.0 \text{ A}$		4.0	0.55	Ω
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5.0 \text{ A}$	4.0	0.8	_	S
Input capacitance		C <sub>iss</sub>		_	1340	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 10 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		160		
Output capacitance		C <sub>oss</sub>			490	_	
Switching time	Rise time	tr	$V_{GS}^{10 \text{ V}} \downarrow_{D} = 5 \text{ A} \\ 0 \text{ V} \downarrow_{O} \downarrow_{O} \downarrow_{O} \downarrow_{O} \\ R_{L} = 40 \Omega \\ V_{DD} \simeq 200 \text{ V} \\ Duty \le 1\%, t_{W} = 10 \mu \text{ s}$	_	22	_	
	Turn-ON time	t <sub>on</sub>		_	60	_	
	Fall time	t <sub>f</sub>		_	32	_	ns
	Turn-OFF time	t <sub>off</sub>		_	140	_	
Total gate charge (gate-source plus gate-drain)		Qg		_	34	_	nC
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \simeq 320 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	_	18	—	
Gate-drain ("miller") charge		Q <sub>gd</sub>			16		

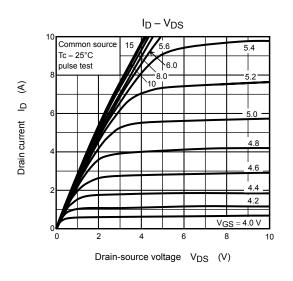
# Source-Drain Ratings and Characteristics (Ta = 25°C)

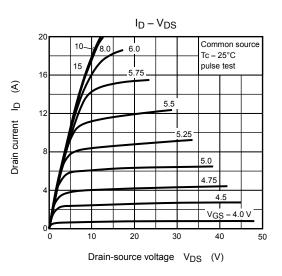
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	—	_	_	10	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	—	_	_	40	А
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 10 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 10 \text{ A}, V_{GS} = 0 \text{ V},$	_	350	_	μS
Reverse recovery charge	Q <sub>rr</sub>	dl <sub>DR</sub> /dt = 100 A/μs	_	3.6	_	μC

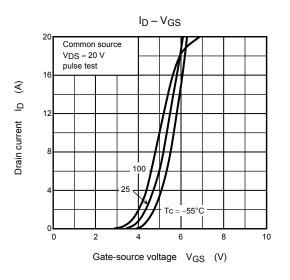
## Marking

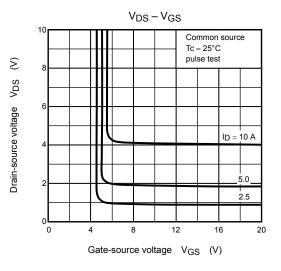


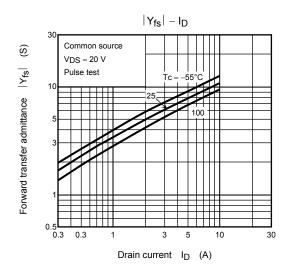
# **TOSHIBA**



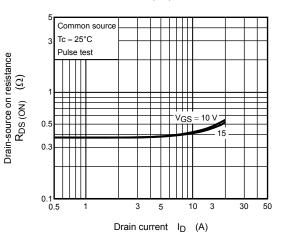




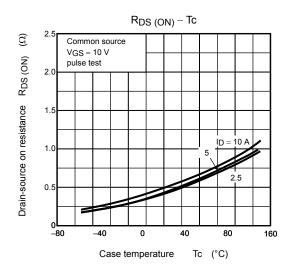


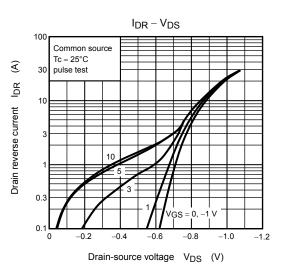


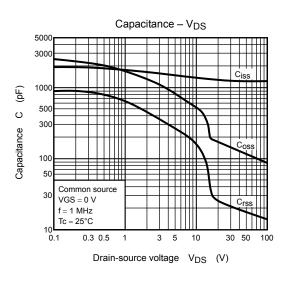
R<sub>DS</sub> (ON) - I<sub>D</sub>

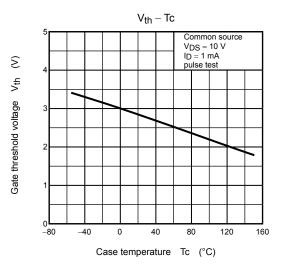


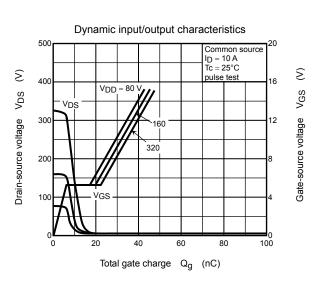
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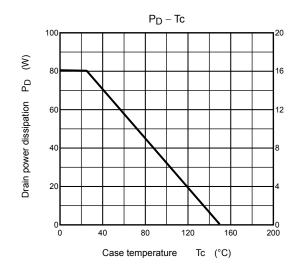


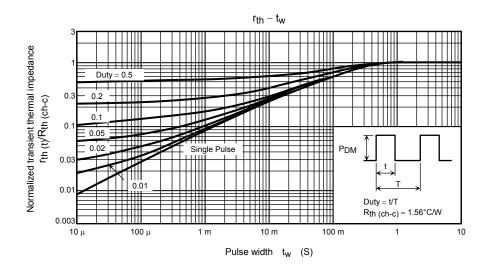




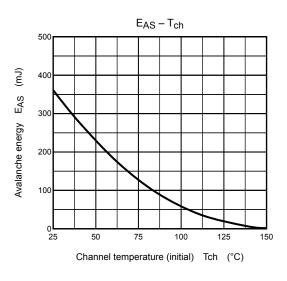


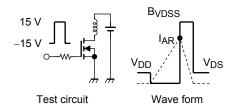


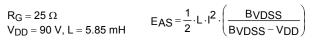




Safe operating area 100 (pulsed) \* 50 In ma 30 00 ID ma (continuous) 10 E Drain current I<sub>D</sub> DC operation 0.5 0.3 0.1 Single nonrepetitive pulse 0.05  $Tc = 25^{\circ}C$ V<sub>DSS</sub> ma 0.03 Curves must be derated linearly with increase in temperature. 0.01 10 100 1000 1 Drain-source voltage V<sub>DS</sub> (V)







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